IV. AMENDMENTS TO THE CLAIMS

1. (currently amended) A wafer support tool for heat treatment comprising:

~~a plurality of wafer support members for supporting a wafer to be heat treated; and~~

a support member holder ~~for holding the wafer support members,~~ in a form of a flat panel and having a central location point and a flat upper surface, the support member holder extending radially from the central location point, the support member holder having a plurality of slit-shaped pinholes formed into the upper surface, disposed apart from the central location point in a radial direction, angularly spaced apart from one another and extending radially relative to the central location point; and

~~wherein the wafer support members each has a contact portion with the wafer, at least one of the contact portions being movable relative to the support member holder~~

a plurality of wafer support members, each one of the plurality of wafer support members having a fitting portion sized to be slidably received in a respective one of the plurality of slit-shaped pinholes and a contact portion integrally connected to the fitting portion and sized to contact and project upwardly from the upper surface of the support member holder when respective ones of the fitting portions are slidably received in respective ones of the plurality of slit-shaped pinholes.

2. (original) The wafer support tool for heat treatment according to claim 1, wherein a configuration of the contact portion is a curved surface convex against the wafer to be heat treated.

3. (previously presented) The wafer support tool for heat treatment according to claim 1, wherein a configuration of the contact portion is spherical or ellipsoidal.

4. (currently amended) The wafer support tool for heat treatment according to claim 1, wherein each one of the plurality of the wafer support ~~member~~ members is a pin~~,~~ and the support member holder is a pin holder for holding the ~~pin and the pin is fitted in a pinhole formed in the pin holder~~ plurality of pins.

5. (original) The wafer support tool for heat treatment according to claim 4, wherein the pin is removable from the pin holder.

6. (previously presented) The wafer support tool for heat treatment according to claim 4, wherein the pin is formed by working a cylindrical body.

7. (previously presented) The wafer support tool for heat treatment according to claim 4, wherein raw material of the pin and the pin holder is SiC, silicon or quartz.

8. (canceled)

9. (canceled)

10. (canceled)

11. (previously presented) The wafer support tool for heat treatment according to claim 4, wherein the pin holder is disc-shaped or ring-shaped.

12. (currently amended) The wafer support tool for heat treatment according to claim 11, wherein the pin holder is disc-shaped and a circular pinhole is formed in the ~~center position~~ central location position thereof.

13. (canceled)

14. (canceled)

15. (canceled)

16. (canceled)

17. (canceled)

18. (canceled)

19. (currently amended) The wafer support tool for heat treatment according to claim 1, further comprising: support poles for holding ~~the plural~~ a plurality of support member holders; and bases for holding the support poles.

20. (original) The wafer support tool for heat treatment according to claim 19, wherein the support member holders are removable from the support poles.

21. (previously presented) The wafer support tool for heat treatment according to claim 19, wherein material of the support poles and the bases is SiC, silicon or quartz.

22. (previously presented) A heat treatment apparatus having the wafer support tool for heat treatment according to claim 1.

23. (new) The wafer support tool for heat treatment according to claim 1, wherein each one of the plurality of slit-shaped pinholes is rectangularly shaped and has a width extending perpendicularly relative to the radial direction, the width of each one of the plurality of slit-shaped pinholes is at least substantially uniform.

24. (new) The wafer support tool for heat treatment according to claim 1, wherein each one of the plurality of wafer support members is operative to tilt when

received in a respective one of the plurality of slit-shaped pinholes such that, when the fitting portion tilts towards the central location point, the contact portion tilts away from the central location point and, when the fitting portion tilts away from the central location point, the contact portion tilts towards the central location point.